

**AMENDMENTS TO THE SPECIFICATION:**

**Please amend the paragraph beginning at page 24, line 12, as follows:**

Thus, a plurality of envelopers, generally indicated by reference 56 in Fig. [[7]] 7D, can be defined in a lump by the lid members 36 and the surrounding wall members 48 securely attached to each other, and each of the electrical components 46 is accommodated and sealed in a corresponding enveloper 56, resulting in production of the plurality of hollow-package type electronic products on the plate-like substrate 44. After the sealing process as shown in Figs. 7A to 7D is completed, the plate-like substrate 44 carrying the hollow-package type electronic products is removed from the sealing machine, and is subjected to a dicing process in which plate-like substrate 44 is cut such that the hollow-package type electronic products are individually separated from each other.